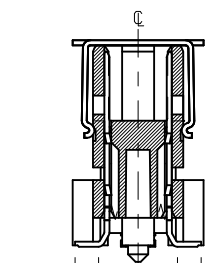
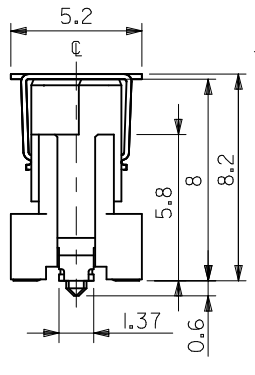
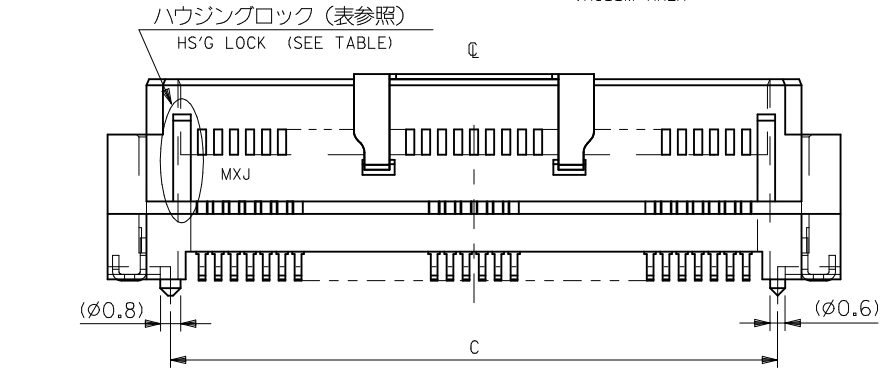
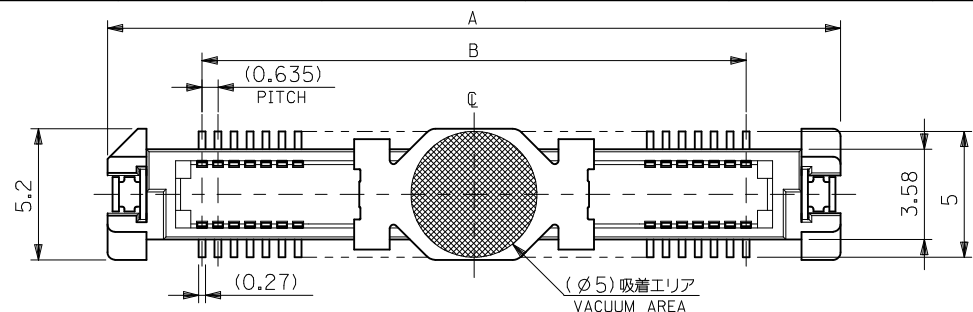
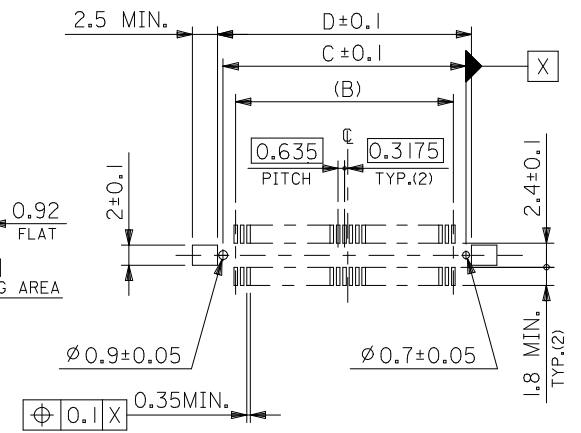


10 9 8 7 6 5 4 3 2 1



半田付け部詳細図  
DETAIL FOR SOLDERING AREA



推奨基板寸法  
RECOMMENDED PCB PATTERN LAYOUT  
(SCALE:2-1)

注) NOTES

- 1.材質 MATERIAL  
ハウジング: ガラス入りPPS、茶色、UL94V-0  
HOUSING: G.F.PPS, BROWN, UL94V-0  
ターミナル: 銅合金 (t=0.2)  
TERMINAL: COPPER ALLOY  
フィッティングネイル: 銅合金 (t=0.2)  
FITTING NAIL: COPPER ALLOY  
吸着カバー: ステンレス (t=0.2)  
VACUUM COVER: STAINLESS STEEL
- 2.メッキ仕様 PLATING  
ターミナル TERMINAL  
接点部: 金メッキ 0.25 μmMIN.  
CONTACT AREA: GOLD 0.25 μmMIN.  
半田付け部: 錫メッキ 1.0 μmMIN.  
SOLDER TAIL AREA: TIN 1.0 μmMIN.  
下地メッキ: ニッケルメッキ 1.5 μmMIN.  
UNDER-PLATING: NICKEL 1.5 μmMIN.
- 3.テールのバラツキ寸法 TAIL COPLANARITY  
テール平坦度は、0.1MAX. とする。  
TAIL COPLANARITY TO BE 0.1MAX.
- 4.本製品は 53649-\*\*\*2 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53649-\*\*\*2

2.メッキ仕様 PLATING

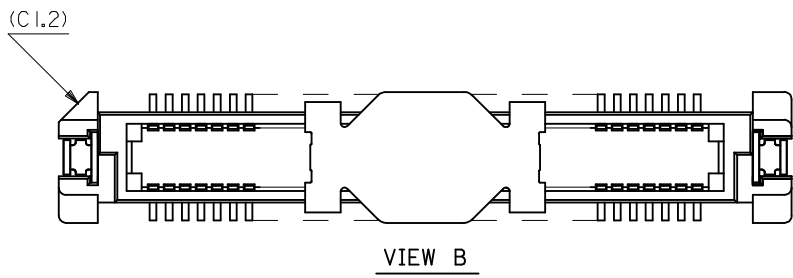
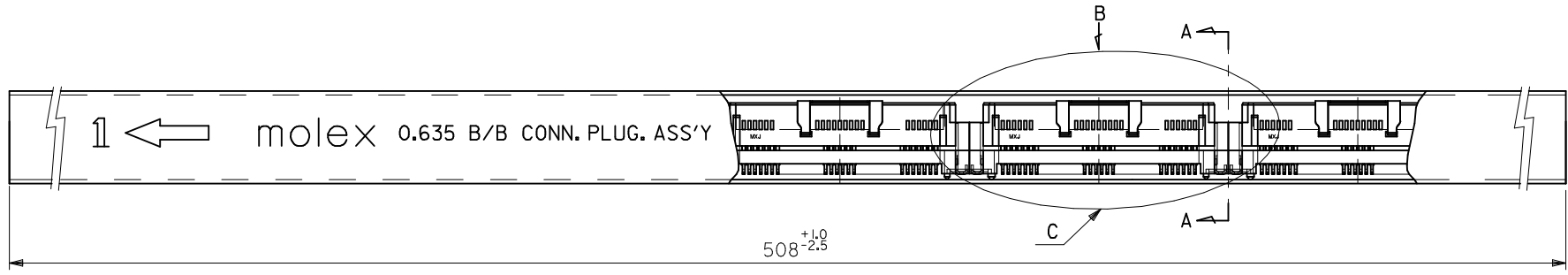
ターミナル TERMINAL  
接点部: 金メッキ 0.25 μmMIN.  
CONTACT AREA: GOLD 0.25 μmMIN.  
半田付け部: 錫メッキ 1.0 μmMIN.  
SOLDER TAIL AREA: TIN 1.0 μmMIN.  
下地メッキ: ニッケルメッキ 1.5 μmMIN.  
UNDER-PLATING: NICKEL 1.5 μmMIN.

フィッティングネイル FITTING NAIL  
錫メッキ 1.0 μmMIN.  
TIN 1.0 μmMIN.  
下地メッキ: ニッケルメッキ 1.0 μmMIN.  
UNDER-PLATING: NICKEL 1.0 μmMIN.

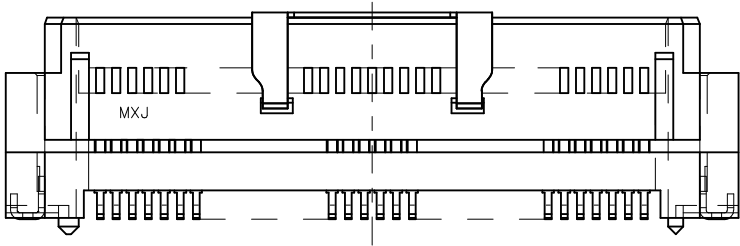
	47.42	46.32	43.815	51.32	—#—	53649-1475	53649-1472	140
無し NO	34.72	33.62	31.115	38.62	53649-1074	53649-1072	53649-1072	100
	28.37	27.27	24.765	32.27	53649-0874	53649-0875	53649-0872	80
有り YES	22.02	20.92	18.415	25.92	53649-0674	53649-0675	53649-0672	60
	15.67	14.57	12.065	19.57	53649-0474	53649-0475	53649-0472	40
	12.5	11.4	8.89	16.4	53649-0374	53649-0375	53649-0372	30
ハウジング HS'G LOCK	D	C	B	A	エンボス梱包 EMBOSSED PACKAGING	スティック梱包 STICK PACKAGING	製品番号 MATERIAL NO.	極数 CKT. NO.
							MODEL NO. 53649-***72	

REVISED EC NO.: J2011009566 DRWN: MKATO 2010/07/30 CHKD: THIRATA 2010/07/30 APPR: MSASAO 2010/08/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. NABEI	DATE '04/02/25	TITLE 0.635 B/B CONN. PLUG HS'G COVER ASS'Y -LEAD FREE-				
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/25	MOLEX INCORPORATED				
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/02/25	DOCUMENT NO. SD-53649-004				
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

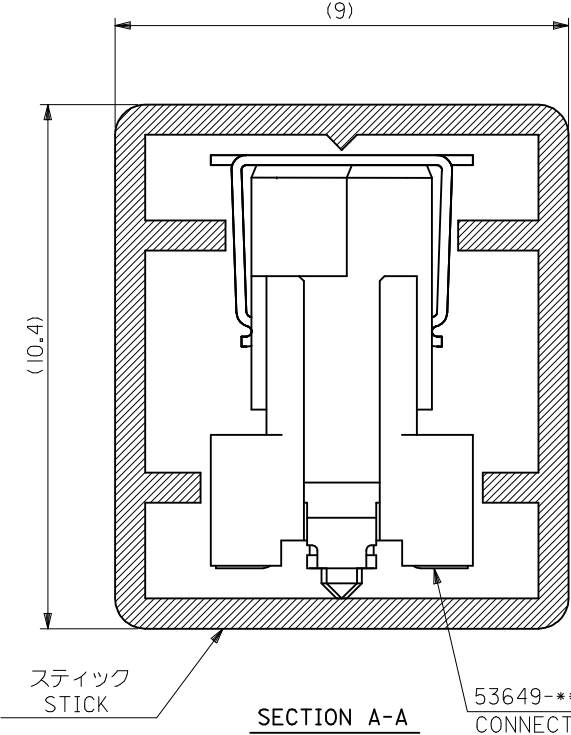
10 9 8 7 6 5 4 3 2 1



VIEW B



DETAIL C



スティック  
STICK

SECTION A-A  
53649-\*\*72  
CONNECTOR

- NOTES.
1. スティック両端はキャップ止め。  
BOTH ENDS WITH CAPS.
  2. 量産対応済の極数のについては、SD-53649-004を参照下さい。  
SEE SD-53649-004 FOR AVAILABLE ITEMS.
  3. 本製品は53649-\*\*\*5の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53649-\*\*\*5

9	53649-1475	140
14	↑ -0875	80
24	↓ -0475	40
29	53649-0375	30
梱包数量 QUANTITY	MATERIAL NO.	極数 CIRCUIT
	MODEL NO.	53649-006

REVISED EC NO: J2009-0280 DRWN: NAKAMURA 2008/08/01 CHKD: T. HARUYAMA 2008/08/01 APPR: NUKITA 2008/12/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY M. NABEI	DATE '04/2/25	TITLE 0.635 B/B CONN. PLUG HSG ASS'Y STICK PACKAGE -LEAD FREE-			
	10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '04/2/25	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY M. SASAO	DATE '04/2/25	DOCUMENT NO. SD-53649-006			
	ANGULAR ± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 1		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

MATERIAL  
材料  
スティック : ポリ塩化ビニル  
STICK : P.V.C.